This paper responds to a non-final Official Action mailed February 11, 2004. Claims 1, 3-18 and 30-34 are pending, of which claim 33 has been cancelled. Applicant notes with appreciation the Examiner's indication that claims 1, 3-18, 30 and 31 are allowed and that claim 33 would be allowable if rewritten in independent form. In view of the foregoing amendments, as well as the following remarks, Applicant respectfully submits that the application is in complete condition for allowance and requests reconsideration of the application in this regard.

Claims 32 and 34 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 3,200,665 (Wells). Applicant has amended claim 32 to incorporate the subject matter of claim 33. Accordingly, Applicant requests that the rejection of claim 32 and claim 34 depending therefrom be withdrawn.

Claim 34 is patentable for an additional reason. Wells discloses a polymer body for a hub that is formed from a "thermoset resinous binder." See Wells at col. 2, lines 24-32. However, the disclosure in Wells is insufficient to anticipate a polymer body is formed from polyamide. A person of ordinary skill in the art would recognize that polyamide is a <a href="thermoplastic">thermoplastic</a> resin. Polyamide is not a <a href="thermoset">thermoset</a> resin as that classification of polymer resins is understood by persons of ordinary skill in the art. A <a href="thermoplastic">thermoplastic</a> resin is capable of softening or fusing when heated and of hardening again when cooled. See e.g., 1407 A <a href="thermoset">thermoset</a> resin has the property of becoming permanently solidified when cured. A <a href="thermoset">thermoset</a> polymer incorporates crosslinked molecular chains, whereas a <a href="thermoplastic">thermoset</a> polymer does not. Because Wells does not teach each and every element in the precise arrangement set forth in

claim 34, Wells does not anticipate independent claim 34 for at least this additional reason.

## CONCLUSION

Applicant has made a bona fide effort to respond to each and every requirement set forth in the Office Action. Accordingly, Applicant respectfully submits that this application is in complete condition for allowance and requests reconsideration of the application in this regard. In the event that any issues remain outstanding, the Examiner is invited to contact the undersigned to expedite issuance of this application.

Applicant does not believe fees are due in connection with filing this communication. If, however, additional fees are necessary as a result of this communication, the Commissioner is hereby authorized to charge any under-payment or fees associated with this communication or credit any over-payment to Deposit Account No. 23-3000.

Respectfully submitted, WOOD, HERRON & EVANS, L.L.P.

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